

2. (*Amended*) The packaged integrated circuit according to claim 1, wherein said packaged integrated circuit comprises an integrated circuit package which houses said at least one radio frequency component and said radio frequency antenna which comprises at least one metal object that is a portion of the package of said packaged integrated circuit.

3. (*Amended*) The packaged integrated circuit according to claim 2, wherein said radio frequency antenna is coupled by a wire bonding to said integrated circuit die.

4. (*Amended*) The packaged integrated circuit according to claim 2, wherein said radio frequency antenna is disposed on a metal lead frame of said integrated circuit package.

5. (*Amended*) The packaged integrated circuit according to claim 1, wherein said radio frequency antenna comprises at least one planar metal pattern separated from a grounded metal plane by an insulating layer.

6. (*Amended*) The packaged integrated circuit according to claim 5, wherein said planar metal pattern is a metal slot-pattern and said insulating layer is a ceramic layer.

7. (*Amended*) The packaged integrated circuit according to claim 6, wherein said slot pattern comprises a first S-shaped slot.

8. (*Amended*) The packaged integrated circuit according to claim 7, wherein said radio frequency antenna comprises a second S-shaped slot rotated 90 degrees with regard to said first S-shaped slot.

9. (*Amended*) The packaged integrated circuit according to claim 1, wherein said integrated circuit package is a Ball Grid Array package.

10. (*Amended*) The packaged integrated circuit according to claim 1, wherein said integrated circuit package is a Quad Flat Pack package.

11. (*Amended*) The packaged integrated circuit according to claim 1, wherein said integrated circuit package is a Small Outline package.

12. (*Amended*) A radio frequency module comprising at least one packaged integrated circuit according to claim 1.

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**Please add the following new claims:**

13. (*New*) A module, comprising:

an integrated circuit die having at least one radio frequency component;

a radio frequency antenna;

a shield interposed between said integrated circuit die and said radio frequency antenna, wherein said integrated circuit is connected to said radio frequency antenna by metal wiring routed through said shield.

14. (New) The module according to claim 13, wherein said radio frequency antenna is comprised of metal.

15. (New) The module according to claim 13, wherein said radio frequency antenna comprises at least one planar metal pattern separated from a grounded metal plane by an insulating layer.

16. (New) The module according to claim 15, wherein said planar metal pattern is a metal slot-pattern and said insulating layer is ceramic layer.

17. (New) The module according to claim 16, wherein said slot pattern is a first S-shaped slot.

18. (New) The module according to claim 17, wherein said radio frequency antenna comprises a second S-shaped slot rotated 90 degrees with respect to said first S-shaped slot.

2/ 19. (New) The module according to claim 13, wherein said radio frequency antenna comprises a plurality of via holes arranged around the periphery of said antenna.

Sub C5 20. (New) The module according to claim 13, wherein said radio frequency antenna is differentially excited.

b2 21. (New) The module according to claim 13, further comprising an integrated circuit package having a metal lead frame, said integrated circuit package encapsulating said shield and said integrated circuit die.

22. (New) The module according to 21, wherein said radio frequency antenna is disposed on said metal lead frame of said integrated circuit package.

23. (New) The module according to claim 13, wherein said integrated circuit package is a Ball Grid Array package.

D/ 24. (New) The module according to claim 13, wherein said integrated circuit package is a Quad Flat Pack package.

25. (New) The module according to claim 13, wherein said integrated circuit package is a Small Outline package.

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26. (New) The module according to claim 13, wherein said shield is connected to an electrical  
ground.

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